Product Change Notification: MFOL-05BJQC887

Date:

09-Nov-2026

Product Category:

32-Bit Microcontrollers, Ethernet Controllers

Notification Subject:

CCB 8606 Initial Notice: Qualification of ASM1 as an additional assembly site for selected LAN9360, ATSAMV70N19, ATSAMV71N19, ATSAME70N19, ATSAMS70N19B, ATSAME70N21, ATSAMS70N21, ATSAMS70N20, ATSAMV71N21, A7SAMV70N20, A7SAMV71N20, ATSAMV71N21B, ATSAMV70N20, ATSAME70N20B, ATSAME70N20, ATSAME70N20A, ATSAMV70N20A, and ATSAMS70N19 device families available in 100L TFBGA (9x9x1.2mm) package.

Affected CPNs:

MFOL-05BJQC887_Affected_CPN_11092026.pdf
MFOL-05BJQC887_Affected_CPN_11092026.csv

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ASM1 as an additional assembly site for selected LAN9360, ATSAMV70N19, ATSAMV71N19, ATSAME70N19, ATSAMS70N19B, ATSAME70N21, ATSAMS70N21, ATSAMS70N20, ATSAMV71N21, A7SAMV70N20, A7SAMV71N20, ATSAMV71N21B, ATSAMV70N20, ATSAME70N20B, ATSAME70N20, ATSAME70N20A, ATSAMV70N20A, and ATSAMS70N19 device families available in 100L TFBGA (9x9x1.2mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	ASE Inc. (ASEK)	ASE Inc. (ASEK)	ASE Electronics (M) Sdn. Bhd (ASM1)	Yes
Wire Material	Au CuPdAu	Au CuPdAu	Au CuPdAu	No
Die Attach Material	2100AS (PFAS)	2100AS (PFAS)	2100ANP (PFAS-Free)	Yes
Molding Compound Material	KE-G1250LKDS	KE-G1250LKDS		No
Substrate Core Material	CCL-HL832NX (A-HS)	CCL-HL832NX (A-HS)		No
Substrate SM Material	PSR4000 AUS 308	PSR4000 AUS308		No
Solder Ball Material	SAC105	SAC105		No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ASM1 as an additional assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: June 2027

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	November 2026					>	June 2027				
Work Week	45	46	47	48	49		23	24	25	26	27
Initial PCN Issue Date		X									
Qual Report Availability		X									

	November 2026					>	June 2027				
Final PCN Issue Date											X

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: November 09, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach_Explanation.pdf
PCN_MFOL-05BJQC887_Qualification Plan.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

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